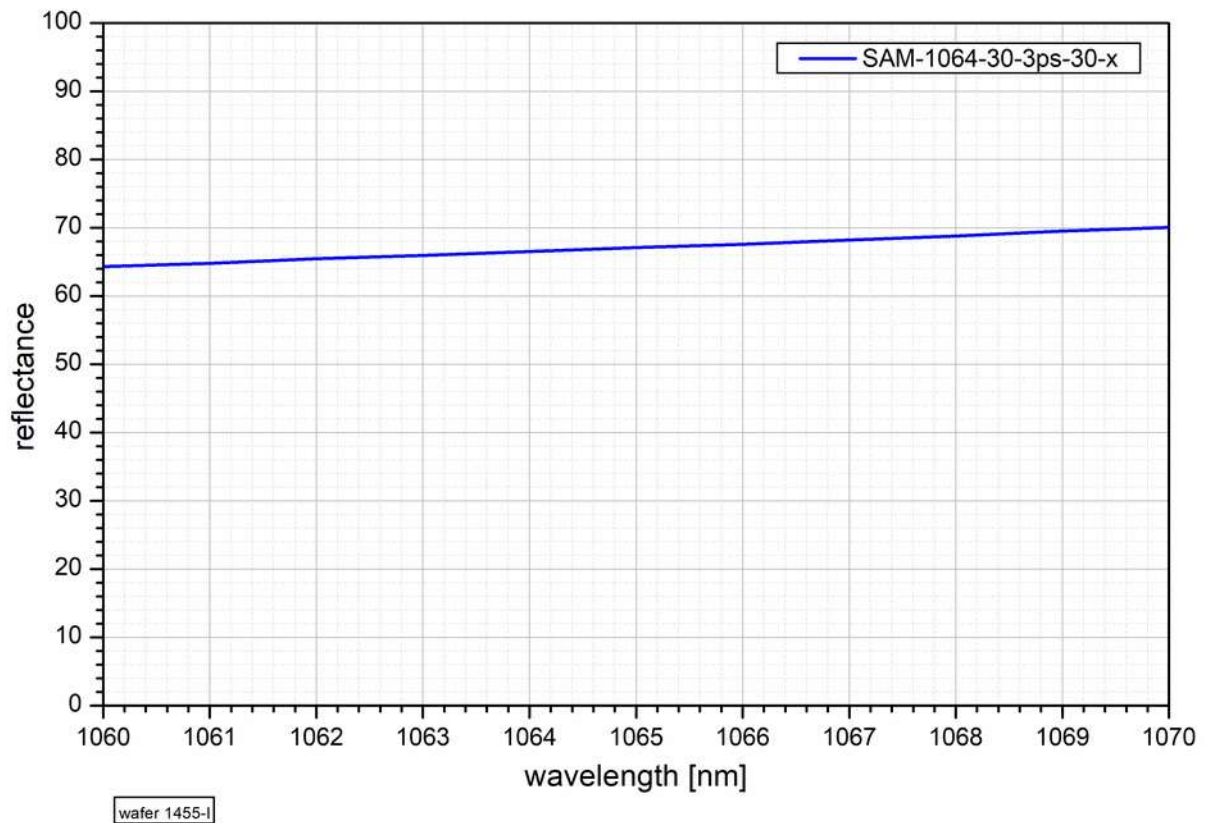


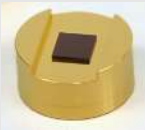

### SAM™ Data Sheet SAM-1064-30-3ps-30-x

	Minimum	Typical Value	Maximum
Operational wavelength $\lambda$		1064 nm	
High reflection band	1020 nm		1080 nm
Absorbance A	24%	30%	36%
Modulation depth $\Delta R$	15 %	24 %	
Saturation fluence $\Phi_{\text{sat}}$	15 $\mu\text{J}/\text{cm}^2$	30 $\mu\text{J}/\text{cm}^2$	50 $\mu\text{J}/\text{cm}^2$
Relaxation time constant $\tau$	1.5 ps	3 ps	5 ps
Damage threshold $\Phi$		800 $\mu\text{J}/\text{cm}^2$	
Absorber Peak Temperature			150°C <sup>1</sup>
Chip thickness	425 $\mu\text{m}$	450 $\mu\text{m}$	475 $\mu\text{m}$
Protection	SAM is protected with a dielectric front layer		

<sup>1</sup> Please make sure that this temperature is not exceeded in pulsed operation shortly after the optical pulse.

#### .Unsaturated spectral reflectance, measured at room temperature with 6° AOI



Mounting Options SAM-1064-30-3ps-30-x	Description
x = 4.0-0	Single chip, unmounted, chip size 4.0mm x 4.0mm
x = 1.0b-0	Batch of 4 unmounted chips, chip size 1.0mm x 1.0mm
x = 1.3b-0	Batch of 4 unmounted chips, chip size 1.3mm x 1.3mm
x = 4.0-12.7g-c / 4.0-12.7g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 12.7 mm $\varnothing$
x = 4.0-25.0g-c / 4.0-25.0g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.0 mm $\varnothing$
x = 4.0-25.4g-c / 4.0-25.4g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.4 mm $\varnothing$
x = 4.0-12.7s-c / 4.0-12.7s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 12.7 mm $\varnothing$
x = 4.0-25.0s-c / 4.0-25.0s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.0 mm $\varnothing$
x = 4.0-25.4s-c / 4.0-25.4s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.4 mm $\varnothing$
x = 4.0-25.0w-c / 4.0-25.0w-e	chip size 4.0mm x 4.0mm, soldered on a water cooled copper heat sink with 25.0 mm diameter
x = 4.0-25.4h-c / 4.0-25.4h-e	chip size 4.0mm x 4.0mm, thin film soldered on a water cooled copper heat sink with 25.0 mm diameter for high power application
-c Center mounting 	-e Edge mounting 
x = FC/(A)PC-SMF	mounted on a 1 m long single mode fiber - FC/PC connector: x = FC/PC-SMF - FC/APC connector: x = FC/APC-SMF available fiber types: HI1060
x = FC/(A)PC-PMF	mounted on a 1 m long polarization maintaining single mode fiber - FC/PC connector: x = FC/PC-PMF - FC/APC connector: x = FC/APC-PMF available fiber types: SM98-PS-U25D
Other chip dimensions are also possible, please ask.	